



RoHS Compliant

**MAX  
260°C**

**MSL  
1**



PRODUCT FAMILY	Material	CAS Number	% Normalize for BOM	Wt. Of BOM Item (g)	% by Wt (Comp. Item)	mg/unit	% by Wt Of Unit 234.10	ppm
<b>767 14</b>								
Alumina Ceramic	Al2O3	1344-28-1	0.8750	0.2048	87.50%	179.2328	76.56%	765625
	SiO2 (silicon dioxide)	14808-60-7			12.50%	25.6047	10.94%	109375
Conductor Thick Film	Ag	7440-22-4	0.0059	0.0014	99.00%	1.3674	0.58%	5841
	Pd	7440-05-3			1.00%	0.0138	0.01%	59
Resistor Thick Film	RuO2	12036-10-1	0.0074	0.0017	30.00%	0.5197	0.22%	2220
	PbO	1317-36-8			10.00%	0.1732	0.07%	740
	SiO2 (silicon dioxide)	14808-60-7			30.00%	0.5197	0.22%	2220
	B2O3	1303-86-2			30.00%	0.5197	0.22%	2220
Notch Conductor Thick Film	Ag	7440-22-4	0.0112	0.0026	72.02%	1.8883	0.81%	8066
	Pd	7440-05-3			4.20%	0.1101	0.05%	470
	Pt	7440-06-4			23.78%	0.6235	0.27%	2663
					100.00%	2.6219		
Lead Wire	Cu	7440-50-8	0.0360	0.0084	100.00%	8.4276	3.60%	36000
Lead Under-Plating	Ni	7440-02-0	0.0100	0.0023	100.00%	2.3410	1.00%	10000
Solder	Ag	7440-22-4	0.0360	0.0084	3.00%	0.2528	0.11%	1080
	Cu	7440-50-8			0.50%	0.0421	0.02%	180
	Sn	7440-31-5			96.50%	8.1326	3.47%	34740
Covercoat	TiO2	13463-67-7	0.0185	0.0043	50.00%	2.1654	0.93%	9250
	Phenolic Resin	55185-45-0			25.00%	1.0827	0.46%	4625
	Epoxy Resin	25068-38-6			25.00%	1.0827	0.46%	4625
	Sum		1.0000 part weight	0.2341	0.2341	100.00%	4.3309	
		<b>Totals:</b>		<b>0.2341</b>		<b>234.10</b>	<b>100.00%</b>	<b>1000000</b>

RoHS exemption claimed for lead in glass of electronic component